

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number

REISSUE APPLICATION DECLARATION BY THE INVENTOR

Docket Number (Optional)

1100.1138101

As a below named inventor, I hereby declare that:

My residence, mailing address and citizenship are stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is described and claimed in patent number 6,036,872, granted March 14, 2000, and for which a

reissue patent is sought on the invention entitled METHOD FOR MAKING A WAFER-PAIR HAVING SEALED CHAMBERS

the specification of which

☒ is attached hereto.

☐ was filed on _____ as reissue application number _____ / _____
and was amended on _____
(If applicable)

I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.

I verily believe the original patent to be wholly or partly inoperative or invalid, for the reasons described below. (Check all boxes that apply.)

☐ by reason of a defective specification or drawing.

☒ by reason of the patentee claiming more or less than he had the right to claim in the patent.

☐ by reason of other errors.

At least one error upon which reissue is based is described below. If the reissue is a broadening reissue, such must be stated with an explanation as to the nature of the broadening:

I believe it was an error to limit all of the issued independent claims in U.S. Patent No. 6,036,872 to a first "silicon" wafer. My invention should not be limited to "silicon" wafers. As noted in the present specification (see, U.S. Patent No. 6,036,872, column 4, lines 18-23), the wafers may be made from any number of materials, and that the claims should not be limited to a first wafer that is made from silicon or any other material system.

All errors which are being corrected in the present reissue application up to the time of filing of this declaration arose without any deceptive intention on the part of the applicant.

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

(REISSUE APPLICATION DECLARATION BY THE INVENTOR, page 2)

Docket Number (Optional)
1100.1138101

All errors corrected in this reissue application arose without any deceptive intention on the part of the applicant. As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the United States Patent and Trademark Office connected therewith.

Name(s)	Registration Number
John G. Shudy, Jr.	31,214
Brian N. Tufte	38,638

Correspondence Address: Direct all communications about the application to:

☒ Customer Number 000128

Type Customer Number here

Place Customer Number Bar
Code Label here

<input type="checkbox"/> Firm or Individual Name				
Address				
Address				
City		State		Zip
Country				
Telephone		Fax		

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine and imprisonment, or both, under 18 U.S.C. 1001, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this declaration is directed.

Full name of sole or first inventor (given name, family name)

R. Andrew Wood

Inventor's signature



Date

10/31/01

Residence

Bloomington, Minnesota

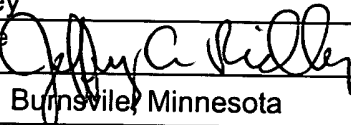
Citizenship US

Mailing Address 150 East Mission Lane, Bloomington, Minnesota 55420

Full name of second joint inventor (given name, family name)

Jeffrey A. Ridley

Inventor's signature



Date

10-31-01

Residence

Burnsville, Minnesota

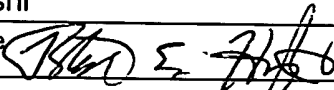
Citizenship US

Mailing Address 13021 Highpoint Curve, Burnsville, Minnesota 55337

Full name of third joint inventor (given name, family name)

Robert E. Higashi

Inventor's signature



Date

10/31/01

Residence

Shorewood, Minnesota

Citizenship US

Mailing Address 20220 Manor Road, Shorewood, Minnesota 55331

☐ Additional joint inventors are named on separately numbered sheets attached hereto.

**REISSUE APPLICATION: CONSENT OF ASSIGNEE;
STATEMENT OF NON-ASSIGNMENT**

Docket Number (Optional)
1100.1138101 (H16-17400)

This is part of the application for a reissue patent based on the original patent identified below.

Name of Patentee(s) Ronald A. Wood et al.

Patent Number 6,036,872

Date Patent Issued March 14, 2000

Title of Invention METHOD FOR MAKING A WAFER-PAIR HAVING SEALED CHAMBERS

1. ☒ Filed herein is a statement under 37 CFR 3.73(b). (Form PTO/SB/96)
2. ☐ Ownership of the patent is in the inventor(s), and no assignment of the patent is in effect.

One of boxes 1 or 2 above must be checked. If multiple assignees, complete this form for each assignee. If box 2 is checked, skip the next entry and go directly to "Name of Assignee".

The written consent of all assignees and inventors owning an undivided interest in the original patent is included in this application for reissue.

The assignee(s) owning an undivided interest in said original patent is/are Honeywell Inc.
and the assignee(s) consents to the accompanying application for reissue.

Name of assignee/inventor (if not assigned)

Honeywell Inc.

Signature



Date

11/6/01

Typed or printed name and title of person signing for assignee (if assigned)

David Hoiriis, Associate General Counsel and Chief Patent Counsel